Adhesive Description

Application Note

B-stage epoxy listed by family

RJ4B

High shear strength epoxy material. Excellent adhesion to glass, metal, plastic, plated metal surfaces, ceramics. Excellent for joining systems with low TCE mismatches. Robust processing — works with a variety of systems including clip and bake, ITS. Typical cure times of 60 minutes at 165C.

RJ9F

Low modulus flexible epoxy material. Good adhesion to plastics, ceramics, metal, plated metal surfaces, glass. Excellent for joining systems with high TCE mismatches, preferred formulation where two dissimilar TCE materials are to be joined, such as glass windows to plastic packages, plastic lids to ceramic hybrid substrates, etc. Typical cure times of 60 minutes at 165C.

RJ9LHS

Electrically conductive, silver filled epoxy for use in attaching metal lids and other lid shield applications. RJ9F base material, similar properties. Must be refrigerated. Cure times / temperatures vary between 135C — 165C, 30 minutes — 2 hours. Good adhesion between metal and plastic / organic based printed circuit boards.

RJ9FCCD

Optical Image Sensor epoxy formulation. Excellent adhesion between glass and ceramic and glass and thermoplastics. Good adhesion to thermosetting plastic materials. Low temperature cures — from 100C — 150C, from 30 minutes — 2 hours. Offers superior moisture resistance over competitive materials. Material must be refrigerated.

Quickbond™

Fast cure epoxy material. Faster cure times designed for use with our ITS (Isothermal Seal Systems) and AITS (Automatic Iso Thermal Seal Systems). Not designed for use with clip and bake systems, compatible with some fixture systems. Material must be refrigerated. Typical cure times of 4 minutes in ITS unit with no post cure.

LM2001

Low moisture absorbing epoxy formulation. Excellent adhesion to glass, ceramic, thermoplastics. Good adhesion to thermosetting plastic materials. Low temperature cures ~150C, from 30 minutes — 2 hours. Offers superior moisture resistance over competitive materials. Material must be refrigerated.

Thermout™

Thermally conductive dielectric material for use primarily in High performance FC devices. Designed to maintain thermal contact between a silicon die and a metal or ceramic cover. They are also excellent for use on heat sink or direct attach applications. Excellent adhesion between metal, plated metal, ceramic, and silicon. Material must be refrigerated. They are designed to exhibit elastomer like behavior at elevated temperatures.

Liquid Materials

RJLR8

Two-part room temperature cure spot repair material. Pot life from 2 hours — 4 hours, requires 24 hour ambient cure, requires subsequent post-cure same as base epoxy material. Performance characteristics match base epoxy material. Available in 2g, 10g single use kits.